

# EB1620JA10-19.200M TR [Click part number to visit Part Number Details page](#)

## REGULATORY COMPLIANCE (Data Sheet downloaded on Dec 6, 2018)



◀ Click badges to download compliance docs

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.



## ITEM DESCRIPTION

Automotive Grade Quartz Crystal Resonator 1.6mm x 2.0mm x 0.55mm 4 Pad Ceramic Surface Mount (SMD)  
19.200MHz ±15ppm at 25°C, ±30ppm over -40°C to +85°C 10pF Parallel Resonant



## ELECTRICAL SPECIFICATIONS

Nominal Frequency	19.200MHz
Frequency Tolerance/Stability	±15ppm at 25°C, ±30ppm over -40°C to +85°C
Aging at 25°C	±3ppm/year Maximum
Load Capacitance	10pF Parallel Resonant
Shunt Capacitance	3pF Maximum
Equivalent Series Resistance	200 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	100µWatts Maximum
Spurious Response	-3dB Minimum (Measured from Fo to Fo +5000ppm)
Storage Temperature Range	-50°C to +150°C
Insulation Resistance	500 Megaohms Minimum (Measured at 100Vdc)

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

## EB1620JA10-19.200M TR [Click part number to visit Part Number Details page](#)

### MECHANICAL DIMENSIONS (all dimensions in millimeters)



Note: Chamfer not shown.

PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

LINE	MARKING
1	19.20
2	XXX XXX=Ecliptek Manufacturing Identifier

### Seam Sealed

Terminal Plating Thickness: Gold (0.3 to 1.0µm) over Nickel (1.27 to 8.89µm).

### Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

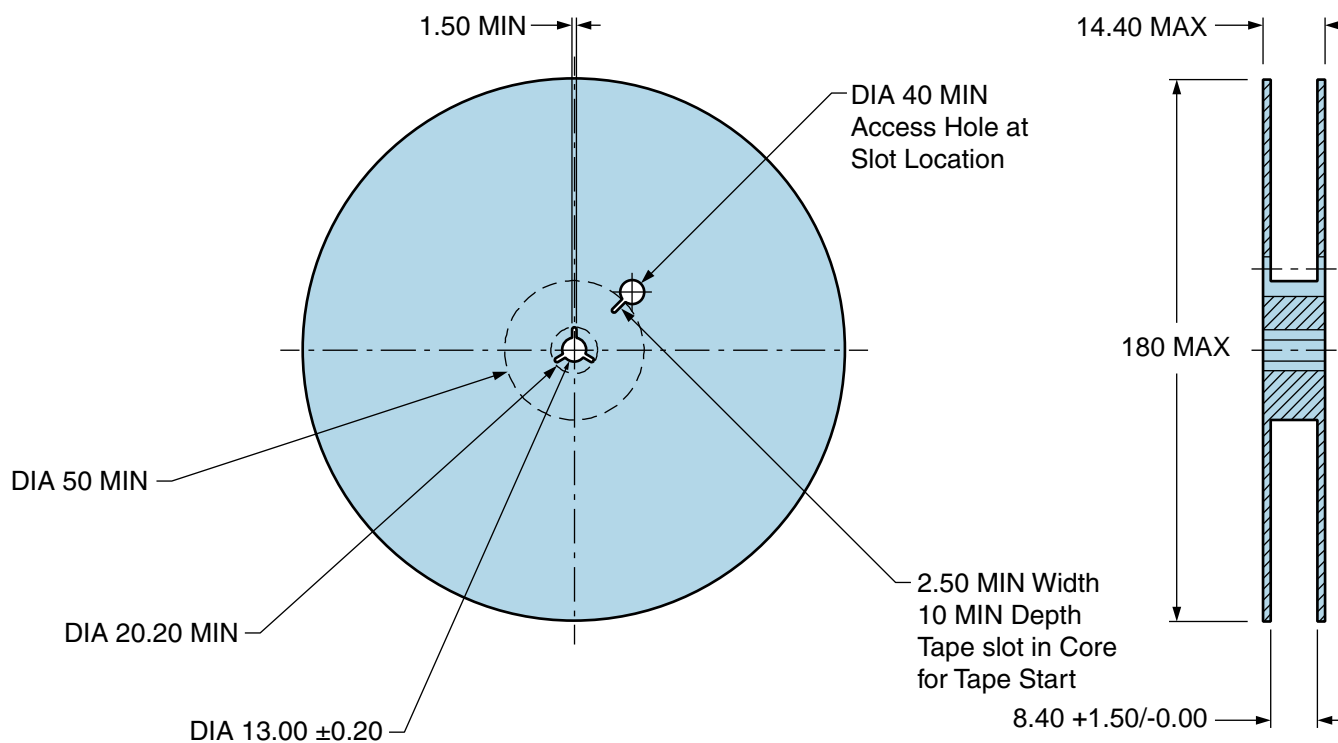
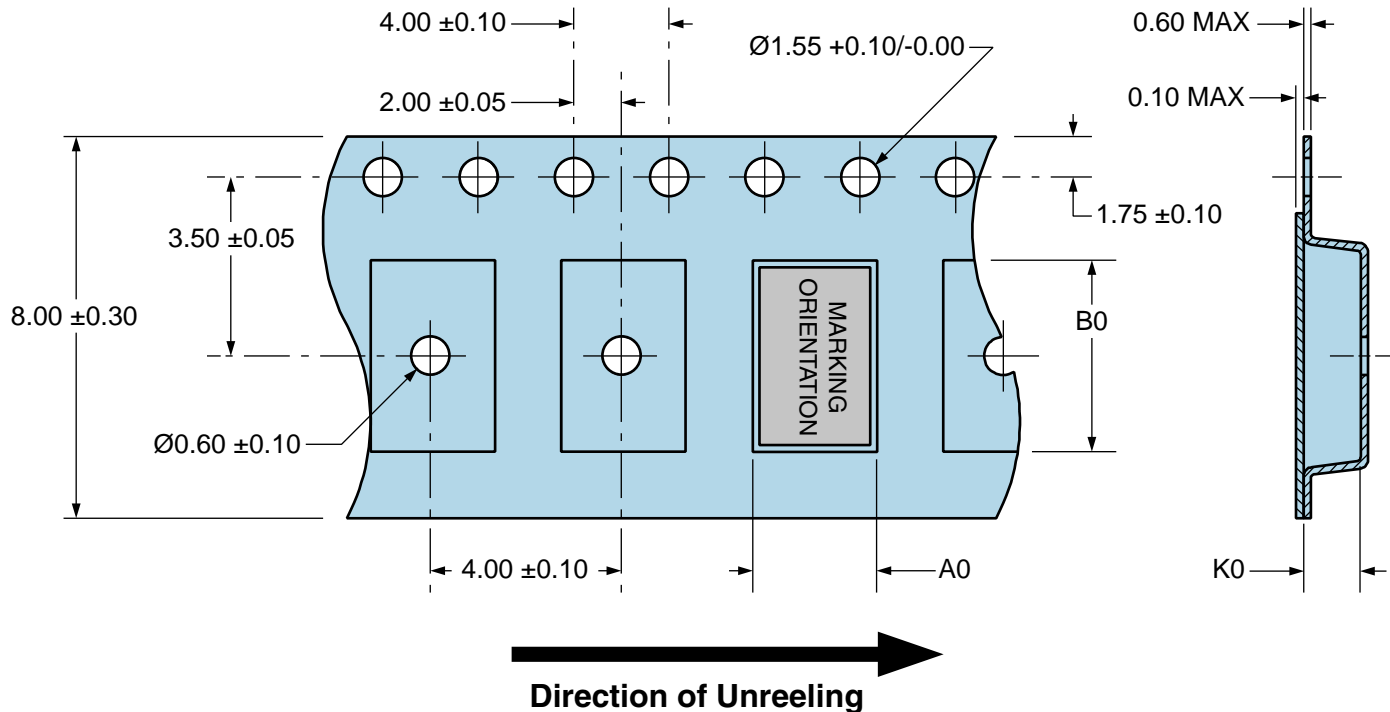
# EB1620JA10-19.200M TR

## Tape & Reel Dimensions

Quantity Per Reel: 3,000 units

All Dimensions in Millimeters

Compliant to EIA-481



# EB1620JA10-19.200M TR [Click part number to visit Part Number Details page](#)

## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

<b><math>T_S</math> MAX to <math>T_L</math> (Ramp-up Rate)</b>	3°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_S$ MIN)	150°C
- Temperature Typical ( $T_S$ TYP)	175°C
- Temperature Maximum ( $T_S$ MAX)	200°C
- Time ( $t_s$ MIN)	60 - 180 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	3°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	217°C
- Time ( $t_L$ )	60 - 150 Seconds
<b>Peak Temperature (<math>T_P</math>)</b>	260°C Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (<math>T_P</math> Target)</b>	250°C +0/-5°C
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	20 - 40 Seconds
<b>Ramp-down Rate</b>	6°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	8 Minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

# EB1620JA10-19.200M TR [Click part number to visit Part Number Details page](#)

## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 245°C

<b><math>T_s</math> MAX to <math>T_L</math> (Ramp-up Rate)</b>	5°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_s$ MIN)	N/A
- Temperature Typical ( $T_s$ TYP)	150°C
- Temperature Maximum ( $T_s$ MAX)	N/A
- Time ( $t_s$ MIN)	30 - 60 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	5°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	150°C
- Time ( $t_L$ )	200 Seconds Maximum
<b>Peak Temperature (<math>T_P</math>)</b>	245°C Maximum
<b>Target Peak Temperature (<math>T_P</math> Target)</b>	245°C Maximum 2 Times / 230°C Maximum 1 Time
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
<b>Ramp-down Rate</b>	5°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	N/A
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

## X-ON Electronics

Largest Supplier of Electrical and Electronic Components

*Click to view similar products for [Resonators](#) category:*

*Click to view products by [Ecliptek](#) manufacturer:*

Other Similar products are found below :

[B39431R820H210](#) [CSAC2.00MGCM-TC](#) [ECS-HFR-40.00-B-TR](#) [CSTLS4M00G53Z-A0](#) [ZTB455E](#) [ECS-CR2-16.00-A-TR](#) [ECS-HFR-20.00-B-TR](#) [ECS-CR2-20.00-A-TR](#) [RO3164E-3](#) [ASR418S2-T](#) [CSTNE10M0G520000R0](#) [CSTLS8M00G53093-A0](#) [CSTNE12M0G52A000R0](#) [CSTLS18M4X54-A0](#) [CSTLS16M9X53Z-B0](#) [CSTLS24M0X51-A0](#) [CSTLS25M0X51-B0](#) [CSTLS18M0X51-B0](#) [CSTNE8M00G520000R0](#) [CSTLS4M00G53093-A0](#) [CSTLS18M4X53-A0](#) [CSTNE16M0V510000R0](#) [CSTLS30M0X53-B0](#) [CSTLS33M8X53-B0](#) [CSTLS16M9X53-A0](#) [CSTLS6M40G56-B0](#) [CSTLS6M25G56-A0](#) [CSTNE14M7V510000R0](#) [CSTLS18M4X53-B0](#) [CSTLS33M0X51-B0](#) [CSTLS5M50G56-B0](#) [7B008000I01](#) [7D038400I01](#) [TAXM24M2ILDBET2T](#) [TAXM26M2IHDBET2T](#) [146-32.768-12.5-20-20/A](#) [3225-24.00-12-10-10/A](#) [7B009843M01](#) [CM4024M00009T8188028](#) [CF4016M00009T8188042](#) [S32400001B0730D1JB](#) [X252016MLB4SI](#) [Q24FA20H00389](#) [CSTLS16M0X54-B0](#) [CSTLS4M19G56-B0](#) [9AC04194152080D2JB](#) [CST3.58MGW](#) [CSTCR4M91G55B-R0](#) [CSTLS3M68G56-B0](#) [S2100327072090](#)